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PATENT
2557-000220/US

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Sang-Hyeop LEE et al. Conf.: 7420
Appl. No.: 10/772,311 Group: 1732
Filed: February 6, 2004 Examiner: Ortiz, Angela
For: MOLDING METHOD AND MOLD FOR
ENCAPSULATING BOTH SIDES OF PCB MODULE
WITH WAFER LEVEL PACKAGE MOUNTED PCB

STATUS INQUIRY

Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314

October 18, 2006

Sir:

Please advise the undersigned as to the status of the above-identified application as follows:

A duplicate copy of the present Status Inquiry is attached hereto. It is respectfully requested that the duplicate copy be marked appropriately to indicate the status of the above-identified application and returned to the undersigned as soon as possible.

Please call the undersigned, at 703-668-8000 if there are any questions with regard to the present request.

Respectfully submitted,

HARNESS, DICKEY & PIERCE, P.L.C.

By

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JAC/EGH:ald

Awaiting Action from Patent Office Examiner

Expected Date for Action is: _____.

Awaiting Decision by Board of Appeals.

Application allowed on _____.

Abandoned per _____.

Other _____.